



# Material Composition Declaration

## EPC2102

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	23.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	19.9310	86.6473	89.2934	866473
	Silicon oxide	7631-86-9	0.0896	0.3895		3895
	Silicon nitride	12033-89-5	0.0321	0.1395		1395
	Gallium nitride	25617-97-4	0.1029	0.4474		4474
	Aluminum	7429-90-5	0.1567	0.6812		6812
	Aluminum nitride	24304-00-5	0.0248	0.1080		1080
	Titanium	7440-32-6	0.0039	0.0169		169
	Titanium nitride	25583-20-4	0.0143	0.0620		620
	Copper	7440-50-8	0.0052	0.0226		226
	Tungsten	7440-33-7	0.0061	0.0267		267
	Polyimide		0.1731	0.7523		7523
Under Bump Metal	Titanium	7440-32-6	0.0015	0.0065	0.5505	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1251	0.5440		5440
Solder Bump	Tin	7440-31-5	2.2310	9.6991	10.1562	96991
	Silver	7440-22-4	0.0934	0.4062		4062
	Copper	7440-50-8	0.0117	0.0508		508
Sum in total:			23.0024	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.